

Product End-of-Life Disassembly Instructions

Product Category: Servers

Marketing Name / Model

[List multiple models if applicable.]

HPE Edgeline EL300 Converged Edge System

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2012/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

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Template Revision A

Tool Description	Tool Size (if applicable)
Torx driver	T10/T15
Philps Driver	#2
Flat Head Screw Driver	Medium
Hexagon Screw Driver	5.0mm
Hex Key	8.0mm

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

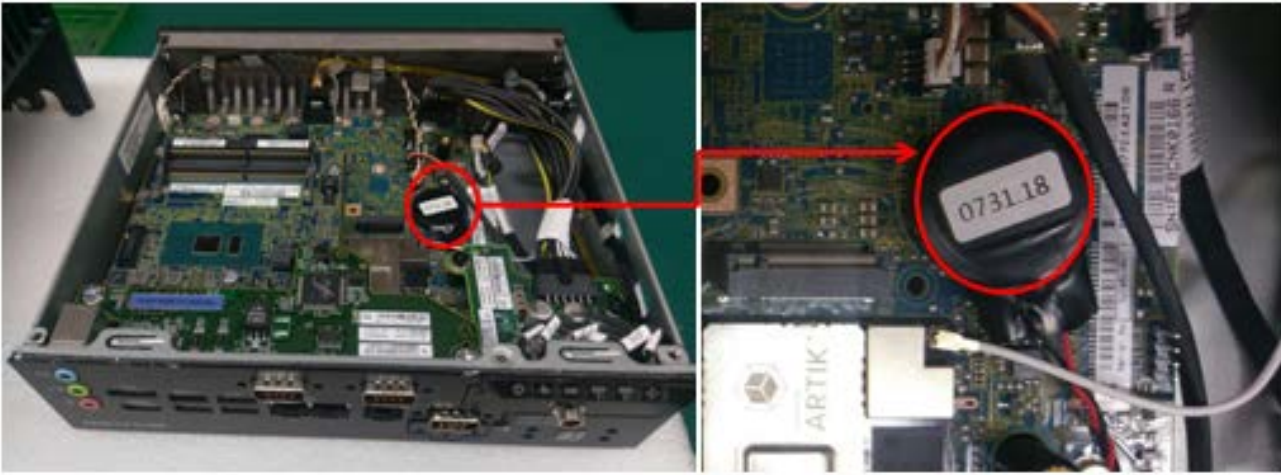
1. The adapter can't be disassemble and please dispose it and cable properly.
2. Use Philps Driver#2 to remove screws and take off the metal piece on bottom side.
3. Use Torx Driver#10 to remove screws on left and right sides.
4. Use Flat Head Screw Driver to remove heatsink.
5. Use Hexagon Screw Driver (5.0mm) and Hex Key (8.0mm) to remove screws and hex nuts.
6. Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
7. Use Torx driver (T10&T15) to remove screws that fixed on 2 PCBA.
8. Use Torx driver (T10&T15) to remove screws fixed on mother board please refer to pictures.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1 – System Coin Battery location

Attachment 2 – Capacitor location by model number of supply

Attachment 1:



Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.

Attachment 2:

